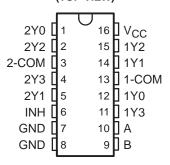
SCLS502C - MAY 2003 - REVISED MAY 2004

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Supports Mixed-Mode Voltage Operation on All Ports
- Fast Switching

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- High On-Off Output-Voltage Ratio
- Low Crosstalk Between Switches
- Extremely Low Input Current
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

D OR PW PACKAGE (TOP VIEW)



description/ordering information

This dual 4-channel CMOS analog multiplexer/demultiplexer is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV4052A handles both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

TA	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 105°C	SOIC - D	Tape and reel	SN74LV4052ATDREP	LV4052ATEP	
-40 C to 105°C	TSSOP - PW	Tape and reel	SN74LV4052ATPWREP	L4052EP	

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

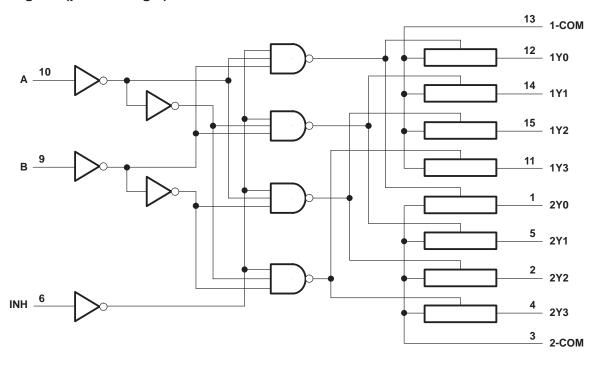
	INPUTS	ON	
INH	В	Α	CHANNEL
L	L	L	1Y0, 2Y0
L	L	Н	1Y1, 2Y1
L	Н	L	1Y2, 2Y2
L	Н	Н	1Y3, 2Y3
Н	Χ	Χ	None



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Switch I/O voltage range, V _{IO} (see Notes 1 and 2)	
Input clamp current, I _{IK} (V _I < 0)	–20 mA
I/O diode current, I _{IOK} (V _{IO} < 0)	–50 mA
Switch through current, $I_T (V_{IO} = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	73°C/W
PW package	108°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT				
Vcc	Supply voltage		2†	5.5	V				
		V _{CC} = 2 V	1.5						
.,	High lovel input voltage, control inputs	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} × 0.7		v				
V_{IH}	High-level input voltage, control inputs	V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7		V				
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7						
		V _{CC} = 2 V		0.5					
	Low level input voltage, control inpute	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$.,				
VIL	Low-level input voltage, control inputs	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V				
		V _{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$					
٧ _I	Control input voltage		0	5.5	V				
V _{IO}	Input/output voltage		0	Vcc	V				
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200					
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V				
			20						
TA	Operating free-air temperature		-40	105	°C				

[†] With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

ı	PARAMETER	TEST CONDITIONS	VCC	MIN MAX	UNIT
	0		2.3 V	225	
ron	On-state switch resistance	$I_T = 2 \text{ mA}$, $V_I = V_{CC}$ or GND, $V_{INH} = V_{IL}$, (see Figure 1)	3 V	190	Ω
SWILOTT TOOLGUTIOC			4.5 V	100	
	5		2.3 V	600	
Peak on-state ron(p) resistance	$I_T = 2 \text{ mA}$, $V_I = V_{CC}$ to GND, $V_{INH} = V_{IL}$	3 V	225	Ω	
	resistance		4.5 V	125	
	Difference in		2.3 V	40	
Δr_{on}	on-state resistance	$I_T = 2 \text{ mA}$, $V_I = V_{CC}$ to GND, $V_{INH} = V_{IL}$		30	Ω
	between switches		4.5 V	20	
lį	Control input current	V _I = 5.5 V or GND	0 to 5.5 V	±1	μΑ
IS(off)	Off-state switch leakage current	$V_I = V_{CC}$ and $V_O = GND$, or $V_I = GND$ and $V_O = V_{CC}$, $V_{INH} = V_{IH}$, (see Figure 2)	5.5 V	±1	μΑ
I _{S(on)}	On-state switch leakage current	$V_I = V_{CC}$ or GND, $V_{INH} = V_{IL}$, (see Figure 3)	5.5 V	±1	μΑ
Icc	Supply current	$V_I = V_{CC}$ or GND	5.5 V	20	μΑ

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74LV4052A-EP DUAL 4-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
tPLH tPHL	Propagation delay time	COM or Y	Y or COM	C _L = 50 pF, (see Figure 4)		12	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		25	ns
tPHZ tPLZ	Disable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		25	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
tPLH tPHL	Propagation delay time	COM or Y	Y or COM	C _L = 50 pF, (see Figure 4)		8	ns
tPZH tPZL	Enable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		18	ns
tPHZ tPLZ	Disable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		18	ns

analog switch characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	FROM	то	TES	ST		T	λ = 25°C	;		
PARAMETER	(INPUT)	(OUTPUT)	CONDIT	TIONS	vcc	MIN	TYP	MAX	UNIT	
_			$C_L = 50 \text{ pF},$		2.3 V		30			
Frequency response (switch on)	COM or Y	Y or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sine	3 V		35		MHz		
(omion on)			(see Note 5 and		4.5 V		50			
			C _L = 50 pF,				-45			
Crosstalk (between any switches)	COM or Y	Y or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sine	wave)	3 V		-45		dB	
(**************************************			(see Note 6 and Figure 7)		4.5 V		-45			
Crosstalk	Crosstells CL = 50 pF,			2.3 V		20				
(control input to signal	INH	COM or Y	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (square wave) (see Figure 8)		3 V		35		mV	
output)					4.5 V		65			
			C _L = 50 pF,		2.3 V		-45			
Feedthrough attenuation (switch off)	COM or Y	Y or COM		$R_L = 600 \Omega$, $f_{in} = 1 \text{ MHz (sine wave)}$ (see Note 6 and Figure 9)			-45		dB	
(5			, , ,				-45			
			C _L = 50 pF,	V _I = 2 V _{p-p}	2.3 V		0.1			
Sine-wave distortion	COM or Y	Y or COM	$R_L = 10 \text{ k}\Omega,$ $f_{\text{in}} = 1 \text{ kHz}$	V _I = 2.5 V _{p-p}	3 V		0.1		%	
			(sine wave) (see Figure 10)	V _I = 4 V _{p-p}	4.5 V		0.1			

NOTES: 5. Adjust f_{in} voltage to obtain 0 dBm at output. Increase f_{in} frequency until dB meter reads -3 dB.

6. Adjust fin voltage to obtain 0 dBm at input.



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operating characteristics, T_A = 25°C

	PARAMETER	TEST CO	TYP	UNIT	
C _{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	11.8	pF

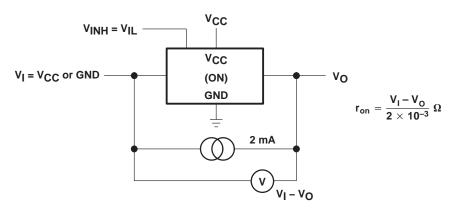


Figure 1. On-State Resistance Test Circuit

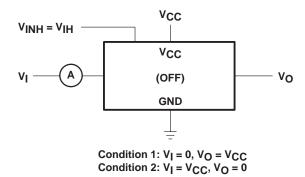


Figure 2. Off-State Switch Leakage-Current Test Circuit

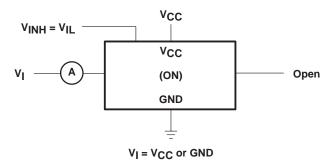


Figure 3. On-State Switch Leakage-Current Test Circuit

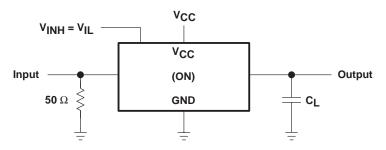


Figure 4. Propagation Delay Time, Signal Input to Signal Output

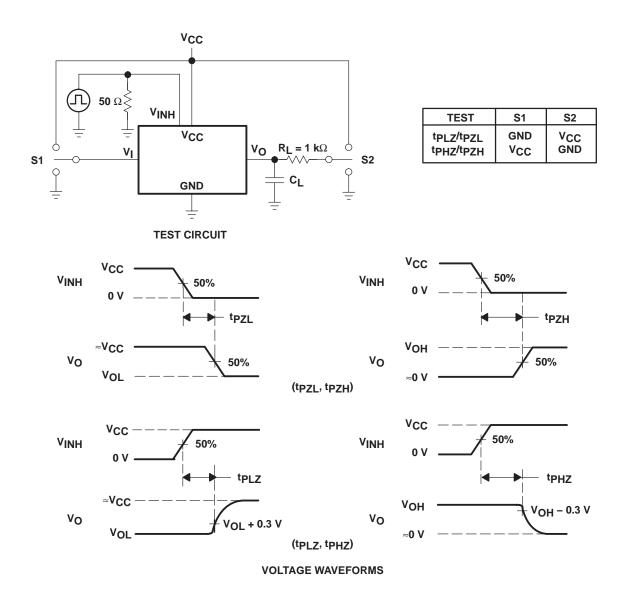
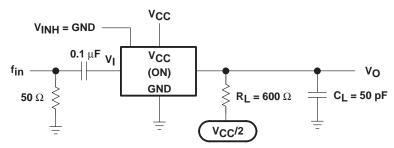


Figure 5. Switching Time (t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}), Control to Signal Output





NOTE A: fin is a sine wave.

Figure 6. Frequency Response (Switch On)

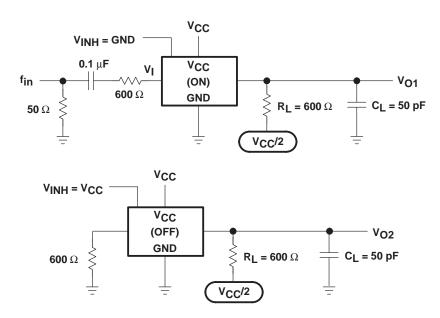


Figure 7. Crosstalk Between Any Two Switches

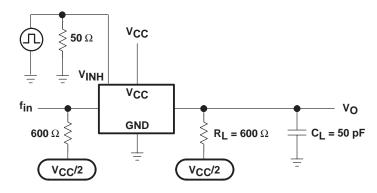


Figure 8. Crosstalk Between Control Input and Switch Output

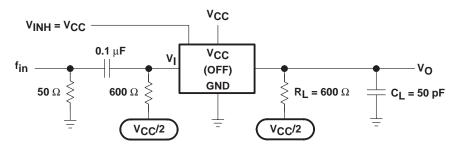


Figure 9. Feedthrough Attenuation (Switch Off)

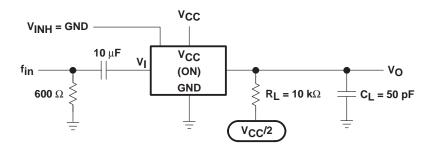


Figure 10. Sine-Wave Distortion



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV4052ATPWREP	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4052EP	Samples
V62/03665-01XE	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4052EP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74LV4052A-EP:

• Automotive: SN74LV4052A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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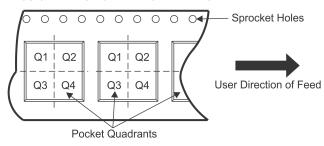
TAPE AND REEL INFORMATION





A0	<u> </u>
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV4052ATPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 16-Oct-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV4052ATPWREP	TSSOP	PW	16	2000	853.0	449.0	35.0



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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